



Material Content Data Sheet



Sales Product Name				BSZ22DN20NS3 G		Issued		1. August 2018	
MA#				MA000862680					
Package				PG-TSDSON-8-1		Weight*		36.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.916	2.53	2.53	25307	25307	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65		
	non noble metal	zinc	7440-66-6	0.009	0.03		261		
	non noble metal	iron	7439-89-6	0.189	0.52		5230		
wire	non noble metal	copper	7440-50-8	7.689	21.24	21.80	212357	217913	
	non noble metal	copper	7440-50-8	0.046	0.13	0.13	1257	1257	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1024	
	plastics	epoxy resin	-	1.909	5.27		52727		
	inorganic material	silicondioxide	60676-86-0	16.589	45.81	51.18	458159	511910	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10221	10221	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2231	2231	
solder	non noble metal	tin	7440-31-5	0.024	0.07		657		
	noble metal	silver	7440-22-4	0.030	0.08		821		
	non noble metal	lead	7439-92-1	1.135	3.14	3.29	31358	32836	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32		
	non noble metal	zinc	7440-66-6	0.005	0.01		130		
	non noble metal	iron	7439-89-6	0.094	0.26		2596		
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.54	10.81	105391	108149	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.078	0.22		2164		
	non noble metal	copper	7440-50-8	3.182	8.79	9.02	87877	90176	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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